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METHOD AND DEVICE FOR THERMALLY CONNECTING THE TERMINAL AREAS OF TWO SUBSTRATES

Entry
Approved
GSE

FIELD OF THE INVENTION

The present invention relates to a method for thermally connecting the terminal areas of a contact substrate to the terminal areas of a carrier substrate, wherein the substrates are, in order to produce the connection, arranged in a connecting position such that the terminal areas are situated opposite one another in the plane of the connection, and wherein the contact substrate is heated to the connecting temperature from its rear side that is situated opposite the terminal areas in order to reach the required connecting temperature in the plane of the connection. The present invention also relates to a device that is suitable for carrying out this